# NPN Silicon Power Darlington

# **High Voltage Autoprotected**

The BU323Z is a planar, monolithic, high-voltage power Darlington with a built-in active zener clamping circuit. This device is specifically designed for unclamped, inductive applications such as Electronic Ignition, Switching Regulators and Motor Control, and exhibit the following main features:

- Integrated High-Voltage Active Clamp
- Tight Clamping Voltage Window (350 V to 450 V) Guaranteed Over the −40°C to +125°C Temperature Range
- Clamping Energy Capability 100% Tested in a Live Ignition Circuit
- High DC Current Gain/Low Saturation Voltages
   Specified Over Full Temperature Range
- Design Guarantees Operation in SOA at All Times
- Offered in Plastic SOT-93/TO-218 Type or TO-220 Packages
- Pb-Free Packages are Available\*

### **MAXIMUM RATINGS**

Rating	Symbol	Max	Unit
Collector-Emitter Sustaining Voltage	V <sub>CEO</sub>	350	Vdc
Collector-Emitter Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current - Continuous - Peak	I <sub>C</sub> I <sub>CM</sub>	10 20	Adc
Base Current – Continuous – Peak	I <sub>B</sub> I <sub>BM</sub>	3.0 6.0	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	150 1.0	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175	°C

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	TL	260	°C

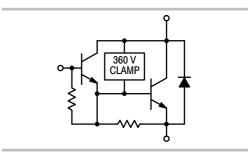
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

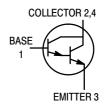


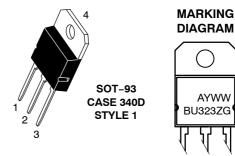
### ON Semiconductor®

http://onsemi.com

# 10 AMPERE DARLINGTON AUTOPROTECTED 360 – 450 VOLTS CLAMP, 150 WATTS







A = Assembly Location

Y = Year

WW = Work Week

G = Pb-Free Package

BU323Z = Device Code

### **ORDERING INFORMATION**

Device	Package	Shipping
BU323Z	SOT-93	30 Units / Rail
BU323ZG	SOT-93 (Pb-Free)	30 Units / Rail

1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS (1)	-		•	•	•	•
Collector–Emitter Clamping Voltage ( $I_C = 7.0 \text{ A}$ ) ( $T_C = -40^{\circ}\text{C}$ to +125°C)		$V_{CLAMP}$	350	_	450	Vdc
Collector–Emitter Cutoff Current $(V_{CE} = 200 \text{ V}, I_B = 0)$		I <sub>CEO</sub>	_	_	100	μAdc
Emitter-Base Leakage Current (V <sub>EB</sub> = 6.0 Vdc, I <sub>C</sub> = 0)		I <sub>EBO</sub>	_	_	50	mAdc
ON CHARACTERISTICS (1)	<del></del>		•	-	•	
Base–Emitter Saturation Voltage ( $I_C = 8.0$ Adc, $I_B = 100$ mAdc) ( $I_C = 10$ Adc, $I_B = 0.25$ Adc)		V <sub>BE(sat)</sub>		_ _	2.2 2.5	Vdc
Collector–Emitter Saturation Voltage ( $I_C = 7.0$ Adc, $I_B = 70$ mAdc) ( $I_C = 8.0$ Adc, $I_B = 0.1$ Adc) ( $I_C = 10$ Adc, $I_B = 0.25$ Adc)	(T <sub>C</sub> = 125°C) (T <sub>C</sub> = 125°C)	V <sub>CE(sat)</sub>	_ _ _ _ _	_ _ _ _ _	1.6 1.8 1.8 2.1 1.7	Vdc
Base–Emitter On Voltage ( $I_C = 5.0$ Adc, $V_{CE} = 2.0$ Vdc) ( $I_C = 8.0$ Adc, $V_{CE} = 2.0$ Vdc)	$(T_C = -40^{\circ}C \text{ to } +125^{\circ}C)$	V <sub>BE(on)</sub>	1.1 1.3	_ _	2.1 2.3	Vdc
Diode Forward Voltage Drop (I <sub>F</sub> = 10 Adc)		V <sub>F</sub>	_	_	2.5	Vdc
DC Current Gain $(I_C = 6.5 \text{ Adc}, V_{CE} = 1.5 \text{ Vdc})$ $(T_C = -40^{\circ}\text{C to } +125^{\circ}\text{C})$ $(I_C = 5.0 \text{ Adc}, V_{CE} = 4.6 \text{ Vdc})$		h <sub>FE</sub>	150 500		 3400	_
DYNAMIC CHARACTERISTICS						
Current Gain Bandwidth (I <sub>C</sub> = 0.2 Adc, V <sub>CE</sub> = 10 Vdc, f = 1.0 MHz)	f <sub>T</sub>	_	_	2.0	MHz	
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	_	200	pF	
Input Capacitance (V <sub>EB</sub> = 6.0 V)	C <sub>ib</sub>	_	_	550	pF	
CLAMPING ENERGY (see notes)	-		•		•	
Repetitive Non–Destructive Energy Dissipated at turn–off: (I <sub>C</sub> = 7.0 A, L = 8.0 mH, $R_{BE}$ = 100 $\Omega$ ) (see Figures 2 and 4)		W <sub>CLAMP</sub>	200	_	_	mJ
SWITCHING CHARACTERISTICS: Inductive Load	I (L = 10 mH)					
Fall Time $(I_C = 6.5 \text{ A, } I_B)$	BE(011) , BE(011) ,		_	625	_	ns
Storage Time $V_{BE(off)} = 0, F$			_	10	30	μs
Cross-over Time V <sub>CC</sub> = 14 V, V <sub>Z</sub> = 300 V)		t <sub>c</sub>		1.7		μs

<sup>(1)</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle = 2.0%.

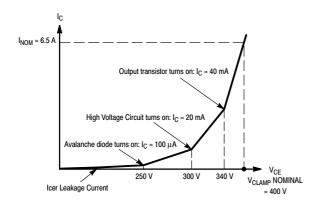


Figure 1.  $I_C = f(V_{CE})$  Curve Shape

L INDUCTANCE MERCURY CONTACTS (8 mH) WETTED RELAY I<sub>C</sub> CURRENT SOURCE  $V_{CE}$ MONITOR (V<sub>GATE</sub>) R<sub>BE</sub> = 100 Ω 0.1 Ω lc. I<sub>B</sub> CURRENT NON MONITOR  $V_{BEoff}$ INDUCTIVE SOURCE I<sub>B2</sub> SOURCE

Figure 2. Basic Energy Test Circuit

By design, the BU323Z has a built–in avalanche diode and a special high voltage driving circuit. During an auto–protect cycle, the transistor is turned on again as soon as a voltage, determined by the zener threshold and the network, is reached. This prevents the transistor from going into a Reverse Bias Operating limit condition. Therefore, the device will have an extended safe operating area and will always appear to be in "FBSOA." Because of the built–in zener and associated network, the  $I_C = f(V_{CE})$  curve exhibits an unfamiliar shape compared to standard products as shown in Figure 1.

The bias parameters,  $V_{CLAMP}$ ,  $I_{B1}$ ,  $V_{BE(off)}$ ,  $I_{B2}$ ,  $I_{C}$ , and the inductance, are applied according to the Device Under Test (DUT) specifications.  $V_{CE}$  and  $I_{C}$  are monitored by the test system while making sure the load line remains within the limits as described in Figure 4.

Note: All BU323Z ignition devices are 100% energy tested, per the test circuit and criteria described in Figures 2 and 4, to the minimum guaranteed repetitive energy, as specified in the device parameter section. The device can sustain this energy on a repetitive basis without degrading any of the specified electrical characteristics of the devices. The units under test are kept functional during the complete test sequence for the test conditions described:

$$I_{C(peak)}$$
 = 7.0 A,  $I_{C}H$  = 5.0 A,  $I_{C}L$  = 100 mA,  $I_{B}$  = 100 mA,  $R_{BE}$  = 100  $\Omega$ ,  $V_{gate}$  = 280 V,  $L$  = 8.0 mH

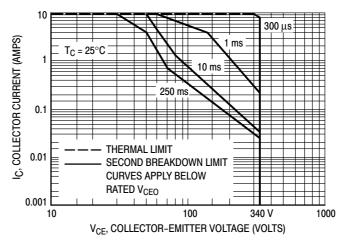
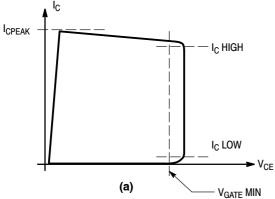
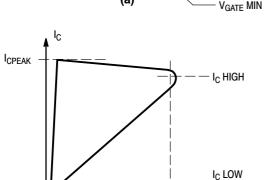
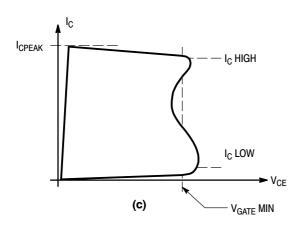


Figure 3. Forward Bias Safe Operating Area

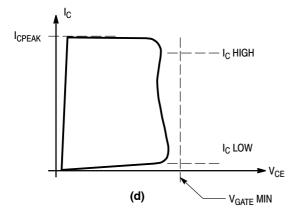






(b)

V<sub>GATE</sub> MIN



The shaded area represents the amount of energy the device can sustain, under given DC biases ( $I_C/I_B/V_{BE(off)}/R_{BE}$ ), without an external clamp; see the test schematic diagram, Figure 2.

The transistor PASSES the Energy test if, for the inductive load and  $I_{CPEAK}/I_B/V_{BE(off)}$  biases, the  $V_{CE}$  remains outside the shaded area and greater than the  $V_{GATE}$  minimum limit, Figure 4a.

The transistor FAILS if the  $V_{CE}$  is less than the  $V_{GATE}$  (minimum limit) at any point along the  $V_{CE}/I_C$  curve as shown on Figures 4b, and 4c. This assures that hot spots and uncontrolled avalanche are not being generated in the die, and the transistor is not damaged, thus enabling the sustained energy level required.

The transistor FAILS if its Collector/Emitter breakdown voltage is less than the  $V_{GATE}$  value, Figure 4d.

Figure 4. Energy Test Criteria for BU323Z

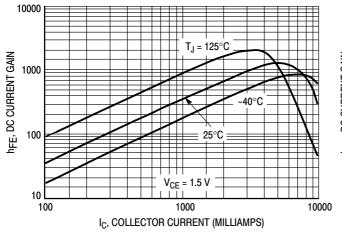


Figure 5. DC Current Gain

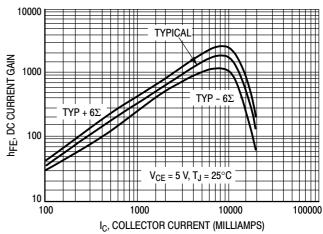


Figure 6. DC Current Gain

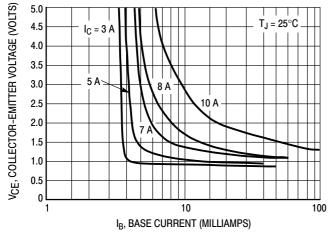


Figure 7. Collector Saturation Region

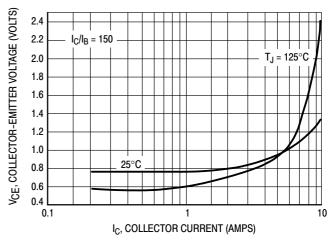


Figure 8. Collector-Emitter Saturation Voltage

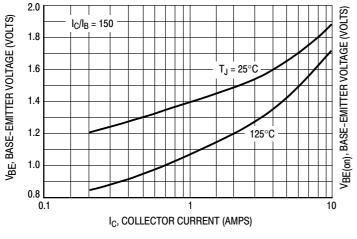


Figure 9. Base-Emitter Saturation Voltage

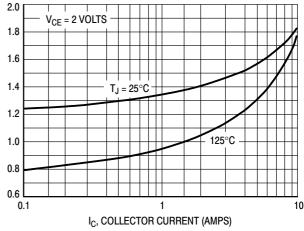
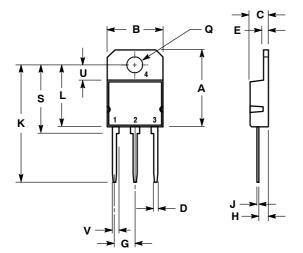


Figure 10. Base-Emitter "ON" Voltages

### PACKAGE DIMENSIONS

### SOT-93 (TO-218) **CASE 340D-02 ISSUE E**



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		20.35		0.801	
В	14.70	15.20	0.579	0.598	
С	4.70	4.90	0.185	0.193	
D	1.10	1.30	0.043	0.051	
E	1.17	1.37	0.046	0.054	
G	5.40	5.55	0.213	0.219	
Н	2.00	3.00	0.079	0.118	
J	0.50	0.78	0.020	0.031	
K	31.00 REF		1.220 REF		
L		16.20		0.638	
Q	4.00	4.10	0.158	0.161	
S	17.80	18.20	0.701	0.717	
U	4.00 REF		0.157 REF		
V	1.75 REF		0.069		

STYLE 1:

PIN 1. BASE

- COLLECTOR
- **EMITTER** 3
- COLLECTOR

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and war engineer trademarks of semiconductor components industries, Ite (SciLLC) solitate services are injective to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### **PUBLICATION ORDERING INFORMATION**

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative